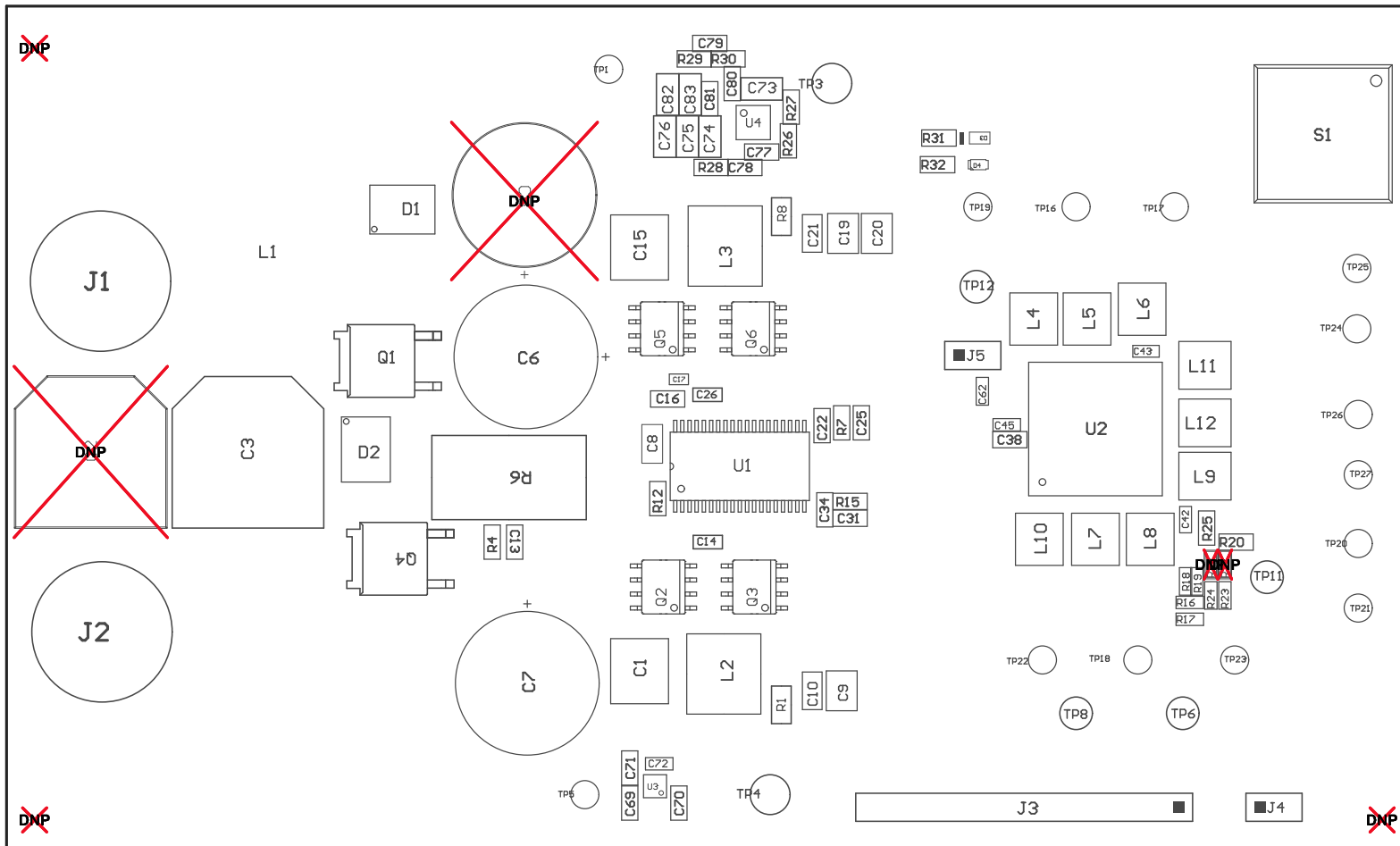
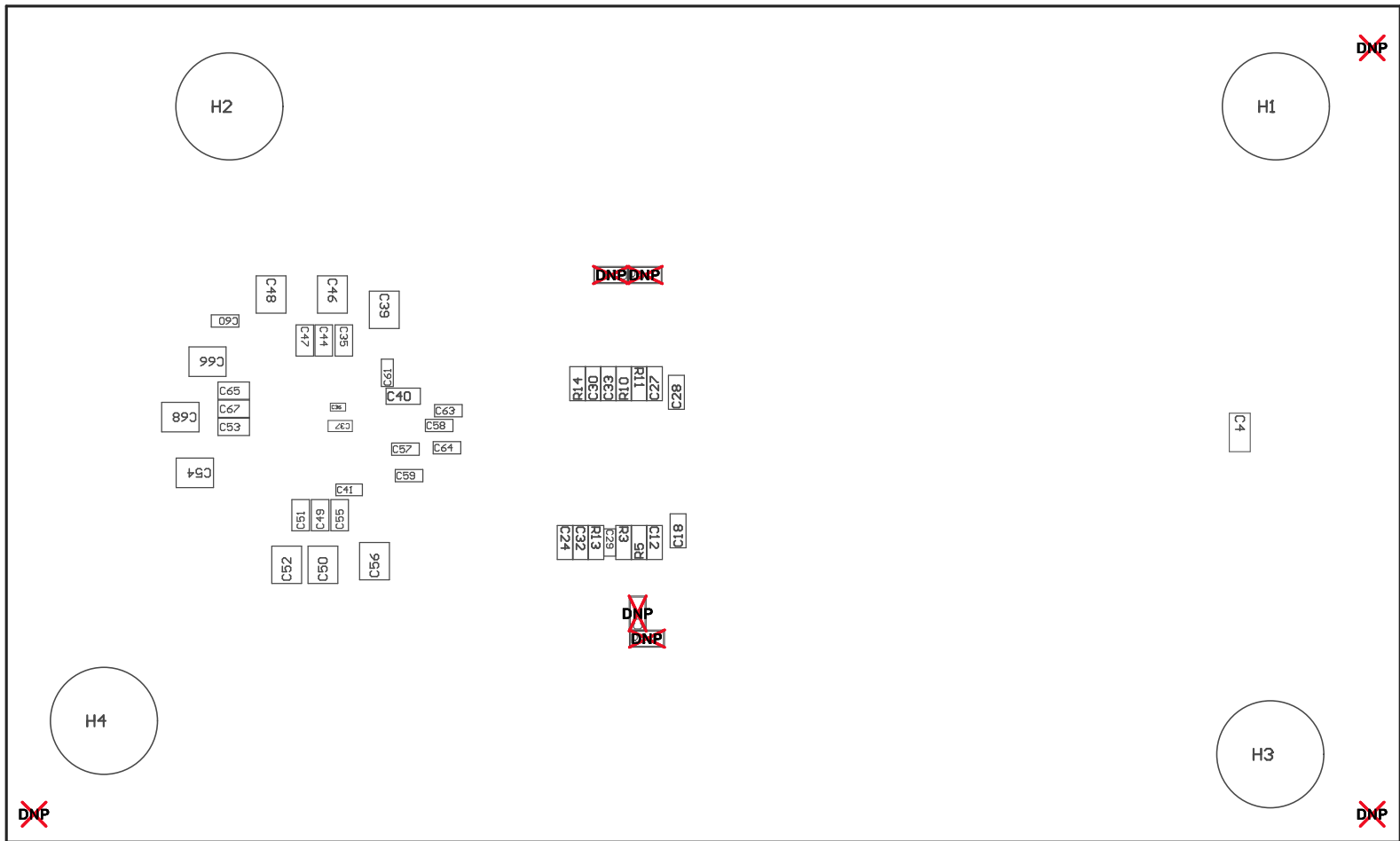


- ZZ1 ■ Place washers H5 & H6 over threaded studs of banana jacks J1 & J2 before assembling onto board to increase clearance below them.
- ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00801	REV: A	SUN REV: Not In VersionControl
PLOT NAME = Top Assembly Drawing	GENERATED : 1/13/2016	9:57:11 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00801	REV: A	SUN REV: Not In VersionControl
PLOT NAME = Bottom Assembly Drawing	GENERATED : 1/13/2016	9:57:13 AM	TEXAS INSTRUMENTS

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